

Kai Fu

List of Publications by Year in descending order

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citing authors

#	ARTICLE	IF	CITATIONS
1	Electrical modeling of carbon nanotube-based shielded through-silicon vias for three-dimensional integrated circuits. International Journal of Numerical Modelling: Electronic Networks, Devices and Fields, 2021, 34, e2842.	1.9	3
2	On the applicability of two-bit carbon nanotube through-silicon via for power distribution networks in 3D integrated circuits. IET Circuits, Devices and Systems, 2021, 15, 20-26.	1.4	2
3	Modeling of Carbon Nanotube-Based Differential Through-Silicon Vias in 3-D ICs. IEEE Nanotechnology Magazine, 2020, 19, 492-499.	2.0	21
4	Modeling and Characterization of Differential Multibit Carbon-Nanotube Through-Silicon Vias. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 534-537.	2.5	10
5	Mini-Review: Modeling and Performance Analysis of Nanocarbon Interconnects. Applied Sciences (Switzerland), 2019, 9, 2174.	2.5	27
6	An Ultracompact Butterworth Low-Pass Filter Based on Vertical Spiral TSV Inductor. , 2019, , .		2
7	Modelling of crosstalk in differential through silicon vias for three-dimensional integrated circuits. IET Microwaves, Antennas and Propagation, 2019, 13, 1529-1535.	1.4	0
8	A Passive Equalizer Design for On-Interposer Differential Interconnects in 2.5D/3D ICs. , 2019, , .		0
9	Analysis of Transmission Characteristics of Copper/Carbon Nanotube Composite Through-Silicon Via Interconnects. Chinese Journal of Electronics, 2019, 28, 920-924.	1.5	8
10	A Compact Passive Equalizer Design for Differential Channels in TSV-Based 3-D ICs. IEEE Access, 2018, 6, 75278-75292.	4.2	7
11	Modeling and Performance Analysis of Shielded Differential Annular Through-Silicon Via (SD-ATSV) for 3-D ICs. IEEE Access, 2018, 6, 33238-33250.	4.2	12
12	A Passive Equalizer Design for Shielded Differential Through-Silicon Vias in 3-D IC. IEEE Microwave and Wireless Components Letters, 2018, 28, 768-770.	3.2	11
13	Vertical Graphene Nanoribbon Interconnects at the End of the Roadmap. IEEE Transactions on Electron Devices, 2018, 65, 2632-2637.	3.0	29
14	The impact of current return path on the signal propagation in the through-silicon via array. , 2017, , .		0
15	Modeling of crosstalk effects in carbon nanotube based differential through-silicon via array. , 2017, , .		0